

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (CURRENTLY AMENDED) A holding structure of a terminal and a substrate, wherein a soldering portion of said terminal is inserted into a connecting hole of said substrate, and a land portion provided on said substrate and said soldering portion of said terminal are held by soldering in a state that said terminal is set upright, said holding structure comprising:

a terminal plate for guiding said soldering portion into said connecting hole to a position opposing said substrate, forming a predetermined clearance;

a positioning hole for holding an intermediate portion of said terminal provided in said terminal plate; and

a retaining portion completely retained in said positioning hole of said terminal plate is provided in said intermediate portion of said terminal, wherein the entirety of said retaining portion is contained within said positioning hole including an upper surface and a lower surface of said retaining portion.

2. (ORIGINAL) The terminal holding structure according to claim 1, wherein said positioning hole of said terminal plate is formed on a terminal press-fitting portion projecting upwardly from an upper surface of said terminal plate.

3. (CURRENTLY AMENDED) A holding structure of a terminal and a substrate, comprising:

a plurality of soldering portions formed to be bifurcated from a soldering proximal portion of said terminal thereby dividing said soldering proximal portion into small portions; and a retaining portion, having an upper and lower surface, which is provided in an intermediate portion of the terminal, wherein the entirety of the retaining portion, including said upper and lower surfaces, is contained within a positioning hole for holding said terminal,

wherein said soldering portions are held on a land portion of said substrate by soldering.

4. (ORIGINAL) The terminal holding structure according to claim 3, wherein connecting holes are respectively formed in said substrate at positions opposing said plurality of soldering portions, and round terminal inserting holes are respectively formed in said land portion at positions opposing said plurality of soldering portions.

5. (ORIGINAL) The terminal holding structure according to claim 4, wherein an indented portion is formed in a peripheral side of a central portion of said land portion located between said terminal inserting holes.

6. (ORIGINAL) A heat dissipating structure for a terminal, wherein one end of said terminal is connectable to a heat generating component and another end of said terminal is soldered in an upright state to a substrate, heat dissipating structure comprising:

a wide flat portion formed by being bent at an intermediate portion of said terminal;

a heat insulating plate disposed at a position opposing said substrate with a predetermined clearance;

wherein said flat portion of said terminal is made capable of freely abutting against a terminal pressing portion provided on said heat insulating plate.

7. (ORIGINAL) The heat dissipating structure for a terminal according to claim 6, wherein a resin plate cover for covering said heat insulating plate is provided in such a manner as to be spaced apart from said heat insulating plate with a predetermined clearance, and said flat portion of said terminal is capable of being freely clamped by said terminal pressing portion of said heat insulating plate and a terminal pressing portion provided on said plate cover.